

ID242 Series

Flash Memory Card

(Model Numbers: ID242xxx)

Spec No.: CPS0002-002

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1. Introduction

This datasheet is for SHARP's ID242 series flash memory card. This datasheet provides all AC and DC characteristics (including timing waveforms) and a convenient reference for the device command set and the card's integrated registers(including the Flash Memory's status registers). This datasheet provides description of the methods which are very helpful for customer to use the card.

2. Features

2.1 Type Flash Memory Card

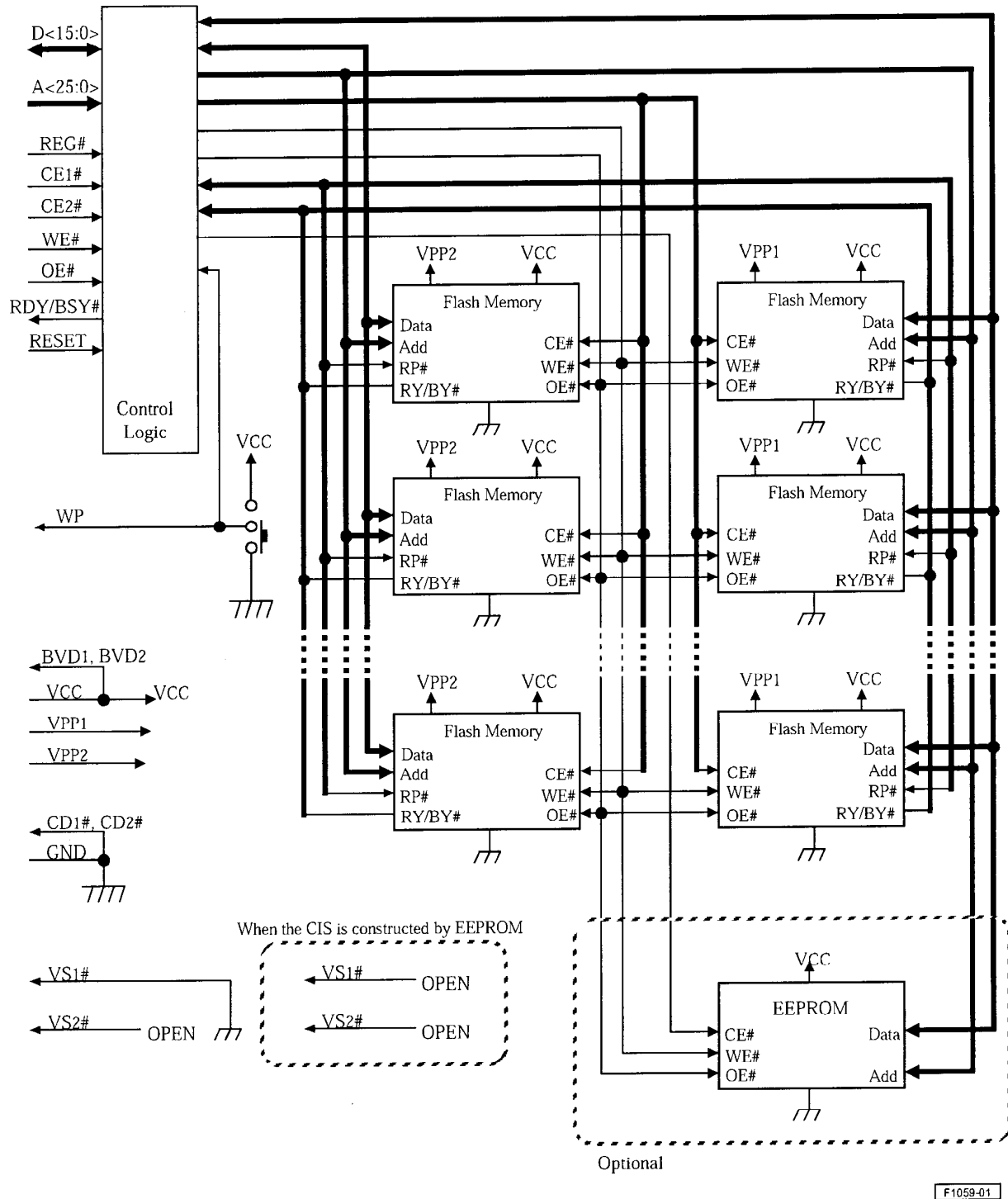
2.2 Overview

		ID242Dxx	ID242Exx	ID242Gxx	ID242Hxx	ID242Kxx	ID242Lxx
Common Memory Capacity	Byte	2Mbyte	4Mbyte	8Mbyte	10Mbyte	16Mbyte	20Mbyte
	Word	1Mword	2Mword	4Mword	5Mword	8Mword	10Mword
Device		LH28F008SC 2devices	LH28F008SC 4devices	LH28F008SC 8devices	LH28F008SC 10devices	LH28F016SC 8devices	LH28F016SC 10devices
Attribute Memory Capacity		2Kbyte (Note:standard CIS is not writable)					
Supply Voltage		Smart Voltage					
Access time		150ns(@V _{cc} =5v) 250ns(@V _{cc} =3.3v)					
Erase Unit		64K word blocks					
Program/Erase Cycles		100,000cycles/Block					
External Dimensions		PCMCIA Type 1 54.0 × 85.6 × 3.3mm					

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- 2.3 Interface Parallel I/O Interface
- 2.4 Function Table See Function Table in page. 9
- 2.5 Pin Connections See Pin Connections in page. 6
- 2.6 Type of Connector Conforms to PCMCIA PC Card Standard 95 Card Use Connector
(Card connector: JC20-J68S-NB3 JAE or FCN-568J068-G/0 Fujitsu)
- 2.7 Operating Temperature 0 to 60°C
- 2.8 Storage Temperature -20 to 65°C
- 2.9 Not designed for rated radiation hardened.

3. Block Diagram



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Figure 1. Block Diagram

4. Pin Connections

Table 1. Pin Connections

PIN No.	SIGNAL	I/O	FUNCTION	ACTIVE	PIN No.	SIGNAL	I/O	FUNCTION	ACTIVE
1	GND		Ground		35	GND		Ground	
2	D ₃	I/O	Data Bit 3		36	CD ₁ #	O	Card Detect 1	LOW
3	D ₄	I/O	Data Bit 4		37	D ₁₁	I/O	Data Bit 11	
4	D ₅	I/O	Data Bit 5		38	D ₁₂	I/O	Data Bit 12	
5	D ₆	I/O	Data Bit 6		39	D ₁₃	I/O	Data Bit 13	
6	D ₇	I/O	Data Bit 7		40	D ₁₄	I/O	Data Bit 14	
7	CE ₁ #	I	Card Enable 1	LOW	41	D ₁₅	I/O	Data Bit 15	
8	A ₁₀	I	Address Bit 10		42	CE ₂ #	I	Card Enable 2	LOW
9	OE#	I	Output Enable	LOW	43	VS ₁ #	O	Voltage Sense 1	
10	A ₁₁	I	Address Bit 11		44	RFU		Reserved	
11	A ₉	I	Address Bit 9		45	RFU		Reserved	
12	A ₈	I	Address Bit 8		46	A ₁₇	I	Address Bit 17	
13	A ₁₃	I	Address Bit 13		47	A ₁₈	I	Address Bit 18	
14	A ₁₄	I	Address Bit 14		48	A ₁₉	I	Address Bit 19	
15	WE#	I	Write Enable	LOW	49	A ₂₀	I	Address Bit 20	
16	RDY/BSY#	O	Ready Busy	LOW	50	A ₂₁	I	Address Bit 21	
17	V _{CC}		Supply Voltage		51	V _{CC}		Supply Voltage	
18	V _{PP1}		Program Voltage		52	V _{PP2}		Program Voltage	
19	A ₁₆	I	Address Bit 16		53	A ₂₂	I	Address Bit 22	
20	A ₁₅	I	Address Bit 15		54	A ₂₃	I	Address Bit 23	
21	A ₁₂	I	Address Bit 12		55	A ₂₄	I	Address Bit 24	
22	A ₇	I	Address Bit 7		56	A ₂₅	I	Address Bit 25	
23	A ₆	I	Address Bit 6		57	VS ₂ #	O	Voltage Sense 2	
24	A ₅	I	Address Bit 5		58	RESET	I	Reset	HIGH
25	A ₄	I	Address Bit 4		59	RFU		Reserved	
26	A ₃	I	Address Bit 3		60	RFU		Reserved	
27	A ₂	I	Address Bit 2		61	REG#	I	Attribute Memory Select	LOW
28	A ₁	I	Address Bit 1		62	BVD ₂	O	Battery Voltage Detect 2	
29	A ₀	I	Address Bit 0		63	BVD ₁	O	Battery Voltage Detect 1	
30	D ₀	I/O	Data Bit 0		64	D ₈	I/O	Data Bit 8	
31	D ₁	I/O	Data Bit 1		65	D ₉	I/O	Data Bit 9	
32	D ₂	I/O	Data Bit 2		66	D ₁₀	I/O	Data Bit 10	
33	WP	O	Write Protect	HIGH	67	CD ₂ #	O	Card Detect 2	LOW
34	GND		Ground		68	GND		Ground	

5. Signal Description

Table 2. Signal Description

Symbol	I/O	Electrical Interface	Function
A ₀ -A ₂₅	I	Pull-down (250kΩ @ V _{CC} =5V)	ADDRESS INPUTS: These are address bus lines which enable direct addressing of memory on the card. Signal A ₀ is not used in word access mode. The system should NOT access memory beyond the card's density, because the upper addresses are not decoded.
D ₀ -D ₁₅	I/O	Pull-down (250kΩ @ V _{CC} =5V)	DATA INPUT/OUTPUT: D ₀ through D ₁₅ constitute the bi-directional data bus. D ₁₅ is the most significant bit.
CE ₁ #, CE ₂ #	I	Pull-up (250kΩ @ V _{CC} =5V)	CARD ENABLE 1 & 2: CE ₁ # enables D ₀ -D ₇ , CE ₂ # enables D ₈ -D ₁₅ .
OE#	I	Pull-up (250kΩ @ V _{CC} =5V)	OUTPUT ENABLE: Active low signal gating read data from the memory card.
WE#	I	Pull-up (250kΩ @ V _{CC} =5V)	WRITE ENABLE: Active low signal gating write data to the memory card.
RDY/BSY#	O		READY/BUSY OUTPUT: Indicates status of internally timed erase or write activities. ID242 series has two types of Ready/Busy output mode; PCMCIA mode and High-Performance mode. In PCMCIA mode, a high output indicates the memory card is ready to accept accesses. A low output indicates that a device in the memory card is busy. In High-Performance mode, the card outputs low when the card is in default state. A high output indicates at least one of flash memory devices in the card comes to be ready to accept accesses.
CD ₁ #, CD ₂ #	O	Pull-down 0W	CARD DETECT 1 & 2: These signals provide for card insertion detection. The signals are connected to ground internally on the memory card, and will be forced low whenever a card is placed in the socket. The host socket interface circuitry shall supply 10K or larger pull-up resistors on these signal pins.
WP	O	Low: Pull-down 0W High: Pull-up 100kW	WRITE PROTECT: Write Protect reflects the status of the Write Protect switch on the memory card. WP set to high = write protected.
V _{PP1} , V _{PP2}			WRITE/ERASE POWER SUPPLY 1 & 2:
V _{CC}			CARD POWER SUPPLY:
GND			GROUND:
REG#	I	Pull-up (250kW @ V _{CC} =5V)	REGISTER SELECT: Provides access to attribute memory when REG# is low.
RESET	I	Pull-up (250kW @ V _{CC} =5V)	RESET: Active high signal for placing card in Power-On Default State.
BVD ₁ , BVD ₂	O	Pull-up 100kW	BATTERY VOLTAGE DETECT 1 & 2: These signals are pulled high to maintain SRAM card compatibility.
VS ₁ #, VS ₂ #	O	VS ₁ #: Pull-down or N.C. VS ₂ #: N.C.	VOLTAGE SENSE 1 & 2: Notifies the host socket of the CIS's VCC requirements. VS ₁ # is pulled-down to ground when using the standard CIS, that indicate 3.3V operating is available. And when using the EEPROM for CIS, the VS ₂ # is open. That indicate the available operation voltage is 5V only.
RFU			RESERVED FOR FUTURE USE

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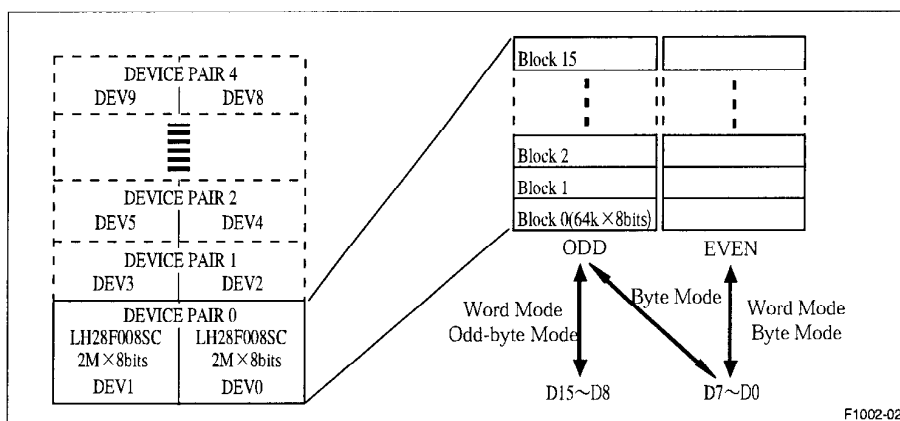
6. Functions

6.1 Common Memory

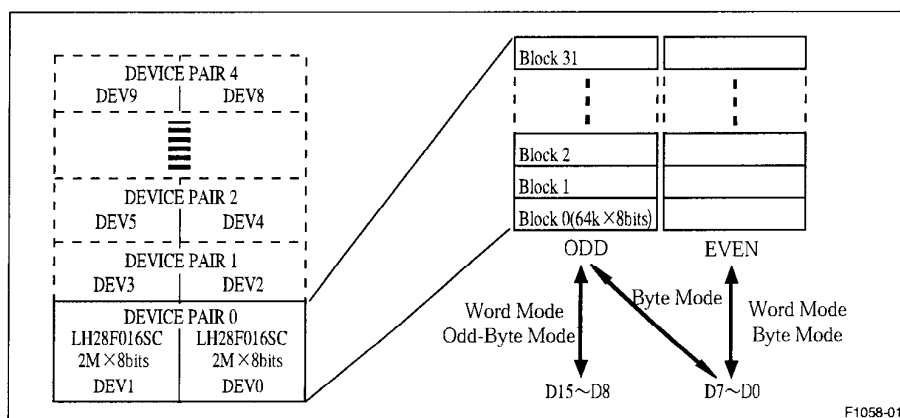
6.1.1 Common Memory Architecture

Figure 2 shows common memory architecture of ID242 series flash memory card. Device pair is consisted of two pieces of flash memory devices. Each device has individually erasable and lockable blocks. All blocks are divided into odd bytes and even bytes.

Each device pair and block is selected by address bits. Table 3 shows definitions of address bits.



(a) For 2, 4, 8, 10MB



(b) For 16MB, 20MB

Figure 2. Common Memory Architecture

Table 3. Address Difications

Address Pifinitions	2MB - 10MB	16MB , 20MB
Select Even / Odd byte in the byte access mode.	A0	
Select address in the block.	A16~A1	
Select a block.	A20~A17	A21~A17
Select a device pair.	A25~A21	A25~A22

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6. 1. 2 Erase

Erase is executed one block at a time. Erasable block size is 64K bytes in byte access mode and 128K bytes in word access mode.

6. 1. 3 Address Decoding

The higher address area of ID242 series flash memory card which goes beyond common memory area is not decoded in common memory access. It means that the system will access to random memory address of the memory card even if system will try to access to the memory address which exceeds memory capacity of the card. Please do not access to the memory address which goes beyond memory capacity of the card.

As an enhanced function, the memory card enables to output invalid data (either of 0000h or FFFFh) when system will access to the memory address which exceeds memory capacity of the card. Please contact our sales & marketing support to find concrete way of setting.

6. 2 Attribute Memory

Figure 3 shows attribute memory map of ID242 series flash memory card. Attribute memory is contained within the Card Control Logic. Attribute memory contains the Card Information Structure (CIS) and Component Management Registers (CMRs). The CIS contains tuple information and is located at even byte addresses beginning with address 0000h (Please refer to section 7). The standard CIS of ID242 series flash memory card is hardwired and is for read only. As an enhanced function, the hardwired CIS area is switchable to EEPROM so that customer can program required CIS. Please contact our sales & marketing support to find concrete way of setting. The CMRs are located at even byte addresses beginning with address 4000h (Please refer to section 9).

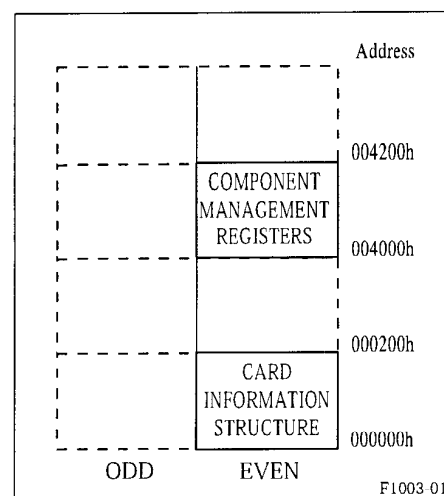


Figure 3. Attribute Memory Map

6.3 Function Table

6.3.1 Common Memory Access

Table 4. Common Memory Access

Mode	REG#	CE ₂ #	CE ₁ #	A ₀	OE#	WE#	D ₁₅₋₈	D ₇₋₀
Stand-by	X	H	H	X	X	X	High-Z	High-Z
Byte Read	H	H	L	L	L	H	High-Z	Even
	H	H	L	H	L	H	High-Z	Odd
Word Read	H	L	L	X	L	H	Odd	Even
Odd Byte Read	H	L	H	X	L	H	Odd	High-Z
Byte Write	H	H	L	L	H	L	Don't care	Even
	H	H	L	H	H	L	Don't care	Odd
Word Write	H	L	L	X	H	L	Odd	Even
Odd Byte write	H	L	H	X	H	L	Odd	Don't care

6.3.2 Attribute Memory Access

Table 5. Attribute Memory Access

Mode	REG#	CE ₂ #	CE ₁ #	A ₀	OE#	WE#	D ₁₅₋₈	D ₇₋₀
Stand-by	X	H	H	X	X	X	High-Z	High-Z
Byte Read	L	H	L	L	L	H	High-Z	Even
	L	H	L	H	L	H	High-Z	XXX
Word Read	L	L	L	X	L	H	XXX	Even
Odd Byte Read	L	L	H	X	L	H	XXX	High-Z
Byte Write	L	H	L	L	H	L	Don't care	Even
	L	H	L	H	H	L	Don't care	Don't care
Word Write	L	L	L	X	H	L	Don't care	Even
Odd Byte write	L	L	H	X	H	L	Don't care	Don't care

XXX:Output data is invalid.

The standard CIS is for read only. Write operation is only for CMRs and CIS on EEPROM

7. Card Information Structure (CIS)

The CIS is contained within attribute memory (Please refer to section 6.2). Table 6 shows standard CIS tuples, but it is for read only. As an enhanced function, the hardwired CIS area is switchable to EEPROM so that customer can program required CIS. Please contact our sales & marketing support to find concrete way of setting.

Table 6. Standard CIS

Address	Value	Description	Address	Value	Description
00h	01h	Device Info (Common Memory)	46h	53h	S :Product Info
02h	04h	Tuple Link	48h	48h	H
04h	57h	Flash Memory	4Ah	41h	A
06h	22h	Access Time 150ns	4Ch	52h	R
08h	06h	Capacity	4Eh	50h	P
	0Eh	2MB	50h	00h	END TEXT
	1Eh	4MB	52h	49h	I
	26h	8MB	54h	44h	D
	3Eh	10MB	56h	32h	2
	4Eh	16MB	58h	34h	4
0Ah	FFh	20MB	5Ah	53h	S
0Ch	1Ch	End of Tuple	5Ch	52h	R
0Eh	05h	Device Info (Common Memory Other Conditions)	5Eh	20h	SPACE
10h	02h	Tuple Link	60h	00h	END TEXT
12h	02h	Conditions 3Vcc	62h	53h	S :Maker Info
12h	57h	Flash Memory	64h	48h	H
14h	32h	Access Time 250ns	66h	41h	A
16h	06h	Capacity	68h	52h	R
	0Eh	2MB	6Ah	50h	P
	1Eh	4MB	6Ch	20h	SPACE
	26h	8MB	6Eh	43h	C
	3Eh	10MB	70h	4Fh	O
	4Eh	16MB	72h	52h	R
18h	FFh	20MB	74h	50h	P
18h	FFh	End of Tuple	76h	4Fh	O
1Ah	17h	Device Info ID (Attribute Memory)	78h	52h	R
1Ch	04h	Tuple Link	7Ah	41h	A
1Eh	1Fh	ROM	7Ch	54h	T
20h	2Ah	Access Time 200ns	7Eh	49h	I
22h	01h	Capacity 2KB	80h	4Fh	O
24h	FFh	End of Tuple	82h	4Eh	N
26h	1Dh	Device Info ID (Attribute Memory)	84h	00h	END TEXT
28h	05h	Tuple Link	86h	FFh	End of Tuple
2Ah	02h	Conditions 3Vcc	88h	1Ah	Configuration Info
2Ch	17h	ROM	8Ah	05h	Tuple Link
2Eh	2Ah	Access Time 200ns	8Ch	01h	2 Bytes Field
30h	01h	Capacity 2KB	8Eh	06h	Last Index of Configuration Table
32h	FFh	End of Tuple	90h	00h	CMRs Base Adress(LSB)
34h	18h	JEDEC Code ID	92h	40h	CMRs Base Adress(MSB)
36h	02h	Tuple Link	94h	0Bh	CMR Mask
38h	89h	Manufacture Code	96h	00h	Null
3Ah	A6h	Device Code	98h	1Bh	Configuration Table Entry 1
3Ch	00h	End of Tuple	9Ah	0Fh	Tuple Link
3Eh	15h	Version Info Level 1	9Ch	01h	Index
40h	23h	Tuple Link	9Eh	02h	Vcc & Vpp
42h	04h	Major Version	A0h	79h	Parameter Selection
44h	01h	Minor Version	A2h	55h	Vcc Voltage 5V

Table 8. Standard CIS (Continued)

Address	Value	Description
A4h	0Ch	Icc Static 1.2mA
A6h	06h	Icc Average 100mA
A8h	06h	Icc Peak 100mA
AAh	23h	Icc Powerdown 50mA
ACh	79h	Parameter Selection
AEh	D5h	Vpp Voltage 5V
B0h	7Dh	NC OK
B2h	1Bh	Ipp Static 150mA
B4h	75h	Ipp Average 80mA
B6h	75h	Ipp Peak 80mA
B8h	52h	Ipp Powerdown 50mA
BAh	1Bh	Configuration Table Entry 2
BCh	0Fh	Tuple Link
BEh	02h	Index
C0h	02h	Vcc & Vpp
C2h	79h	Parameter Selection
C4h	55h	Vcc Voltage 5V
C6h	0Ch	Icc Static 1.2mA
C8h	06h	Icc Average 100mA
CAh	06h	Icc Peak 100mA
CCh	23h	Icc Powerdown 50mA
CEh	79h	Parameter Selection
D0h	8Eh	Vpp Voltage 12V
D2h	7Dh	NC OK
D4h	1Bh	Ipp Static 150mA
D6h	35h	Ipp Average 30mA
D8h	35h	Ipp Peak 30mA
DAh	52h	Ipp Powerdown 50mA
DCh	1Bh	Configuration Table Entry 3
DEh	11h	Tuple Link
E0h	03h	Index
E2h	02h	Vcc & Vpp
E4h	79h	Parameter Selection
E6h	B5h	Vcc Voltage 3.3V
E8h	1Eh	
EAh	0Ch	Icc Static 1.2mA
ECh	7Dh	Icc Average 90mA
EEh	7Dh	Icc Peak 90mA
F0h	1Bh	Icc Powerdown 150mA
F2h	79h	Parameter Selection
F4h	B5h	Vpp Voltage 3.3V
F6h	9Eh	
FAh	1Bh	Ipp Static 150mA
FCh	75h	Ipp Average 80mA
FEh	75h	Ipp Peak 80mA
100h	52h	Ipp Powerdown 50mA
102h	1Bh	Configuration Table Entry 4

Address	Value	Description
104h	10h	Tuple Link
106h	04h	Index
108h	02h	Vcc & Vpp
10Ah	79h	Parameter Selection
10Ch	B5h	Vcc Voltage 3.3V
10Eh	1Eh	
110h	0Ch	Icc Static 1.2mA
112h	7Dh	Icc Average 90mA
114h	7Dh	Icc Peak 90mA
116h	1Bh	Icc Powerdown 150mA
118h	79h	Parameter Selection
11Ah	8Eh	Vpp Voltage 12V
11Ch	7Dh	NC OK
11Eh	1Bh	Ipp Static 150mA
120h	35h	Ipp Average 30mA
122h	35h	Ipp Peak 30mA
124h	52h	Ipp Powerdown 50mA
126h	00h	Null
128h	00h	Null
12Ah	1Eh	Device Geometry
12Ch	06h	Tuple Link
12Eh	02h	Bus: 2bytes
130h	11h	Erase Block: 64Kbytes
132h	01h	Read size: 1byte
134h	01h	Write size: 1byte
136h	01h	Partation: 1block
138h	01h	Non-interleaved
13Ah	20h	Manufacturer ID
13Ch	04h	Tuple Link
13Eh	B0h	Manufacturer Code
140h	00h	
142h	06h	Manufacturer Info: 2MB 4MB 8MB 10MB 16MB 20MB
	07h	
	09h	
	0Ah	
	0Dh	
	0Eh	
144h	33h	Manufacturer Info: DVO
146h	21h	Function Identification
148h	02h	Tuple Link
14Ah	01h	Function: MEMORY
14Ch	00h	System Init: None
14Eh	FFh	End of CIS

8. Card Control

8.1 Reset

The card is in initial state directly after power-up. But we recommend to do reset operation after power-up to make sure to initialize the card.

During block erase, byte write, or lock-bit configuration modes, an active RESET will abort the operation. RDY/BSY# remains low until the reset operation completes. Memory contents being altered are no longer valid; the data may be partially erased or written. The host must wait after RESET goes to logic-Low (V_{IL}) before it can write another command, as determined by t_{PHWL} .

It is important to assert RESET to the card during a system reset. If a CPU reset occurs without a card reset, the host will not be able to read from the card if that card is in a different mode when the system reset occurs.

For example, if an end-user initiates a host reset when the card is in read status register mode, the host will attempt to read code from the card, but will actually read status register data. Sharp's ID242 Series Flash Memory Card allows proper card reset following a system reset through the use of the RESET input.

8.2 Status Register

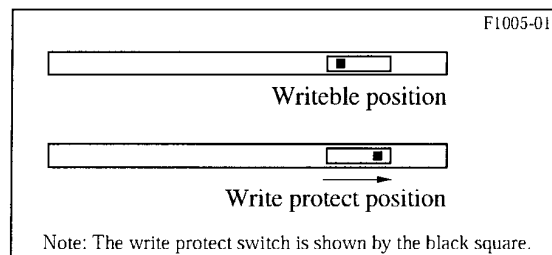
Each flash memory device in the card has status register. The status register may be read to determine when a write, block erase, or lock-bits configuration is complete, and whether that operation completed successfully (please refer to Table 10). It may be read at any time by writing the Read Status Register command (70h, 7070h) into the CUI. In word access mode, the status register data of even byte devices are output to D7~0, and the status register data of odd byte devices are output to D15~8.

8.3 Write Protect Switch

The ID242 Series Flash Memory Card has a write protect switch on the back of the card. When the switch is in the write protect position, the card blocks all writes to the common and attribute memory without Card Management Registers region (see Figure 5).

8.4 Read Identifier Codes / Lock bits Information

Manufacture Code and Device Code are contained within each flash memory device in the memory card. The identifier code operation is initiated by writing the Read Identifier Codes command (90h, 9090h) into the CUI of each memory device. The specific address of each device is necessary to be selected to read these codes (Table 8).



Note: The write protect switch is shown by the black square.

Figure 4. Write Protect Switch

Table 7. Status Register

bit7	bit6	bit5	bit4	bit3	bit2	bit1	bit0
SR.7	SR.6	SR.5	SR.4	SR.3	SR.2	SR.1	SR.0
WSMS	ESS	ECLBS	BWSLBS	VPPS	BWSS	DPS	RFU

<p>SR.7 =WRITE STATE MACHINE STATUS 1 = Ready 0 = Busy</p> <p>SR.6 =ERASE-SUSPEND STATUS 1 = Erase Suspended 0 = Erase in Progress/Completed</p> <p>SR.5 =ERASE AND CLEAR LOCK-BITS STATUS 1 = Error In Block Erasure or Clear Lock-Bits 0 = Successful Block Erase or Clear Lock-Bits</p> <p>SR.4 =BYTE WRITE AND SET LOCK-BIT STATUS 1 = Error in Byte Write or Set Block/Master Lock-Bit 0 = Successful Byte Write or Set Block/Master Lock-Bit</p> <p>SR.3 =VPP STATUS 1 = VPP Low Detect, Operation Abort 0 = VPP OK</p> <p>SR.2 =BYTE WRITE SUSPEND STATUS 1 = Byte Write Suspended 0 = Byte Write in Progress/Completed</p> <p>SR.1 =DEVICE PROTECT STATUS 1 = Master Lock-bit,Block Lock-bit and/or RP# Lock Detected, Operation Abort 0 = Unlock</p> <p>SR.0 =Reserved for Future Enhancements</p>	<p>Notes:</p> <p>Chech RDY/BSY# or SR.7 to determine block erase, word/byte write, or lock-bit configuration completion. SR.6-0 are invalid while SR.7="0".</p> <p>If both SR.5 and SR.4 are "1"s after a block erase or lock-bit configuration attempt, an improper command sequence was entred.</p> <p>SR.3 does not provide a continuous indication of V_{PP} level. The WSM interrogates and indicates the V_{PP} level only after Block Erase, Word/Byte Write, Set Block/Master Lock-bit, or Clear Lock-bits command sequences. SR.3 is not guaranteed to reports accurate feedback only when $V_{PP}=V_{PPH1/2/3}$.</p> <p>SR.1 does not provide a continuous indication of master and block lock-bit values. The WSM interrogates the master lock-bit, block lock-bit, and RP# only after Block Erase, Word/Byte Write, or Lock-bit configuration command sequences. If informs the system, depending on the attempted operation, if the block lock-bit is set, master lock-bit is set, and/or RP# is not 12V. Reading the block lock and master lock configuration codes after writing the Read Identifier Codes commnad indicates master and block lock-bit status.</p> <p>SR.0 is reserved for future use and should be masked out when polling the status register.</p>
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Table 8. Identifier Codes / Lock bits

	Select Device-pair A25-A21	Address in Device A20-A1	Even/Odd A0	Data Output D7-D0	
				2MB - 10MB	16MB , 20MB
Manufacture Identifier Code	DPA	00000h	0:Even 1:Odd	89h	89h
Device Identifier Code	DPA	00001h	0:Even 1:Odd	A6h	AAh
Block Lock Configuration	DPA	X0002h (X: Select Block)	0:Even 1:Odd	BLKD	
				D0: 0=Unlock, 1=Lock D7-D1: Reserved	
Master Lock Configuration	DPA	00003h	0:Even 1:Odd	MLKD	
				D0: 0=Unlock, 1=Lock D7-D1: Reserved	

NOTE: A0 is ignored in word access mode, and D15-D8 outputs the Odd byte data.

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DPA: Address as select device pair
 BLKD: Block Lock Configuration Data
 MLKD: Master Lock Configuration Data

9. Component Management Registers (CMR)

Component Management Registers (CMR) are mapped at even byte locations beginning at address 4000h in attribute memory.

9.1 Configuration Option Register (Address:4000h)

Address	Bit.7	Bit.6	Bit.5	Bit.4	Bit.3	Bit.2	Bit.1	Bit.0
4000h	SRESET	Reserved						
SRESET: 1=Reset State 0=End Reset Cycle								

9.2 Card Configuration Register (Address:4002h)

Address	Bit.7	Bit.6	Bit.5	Bit.4	Bit.3	Bit.2	Bit.1	Bit.0
4002h	Reserved					PWDN	Reserved	
PWDN: 1=Power-Down Device pairs that apointed by Sleep Control Register(4118h-411Ah) are in Power-Down. 0=Power-Up								

9.3 Socket and Copy Register (Address:4006h)

Address	Bit.7	Bit.6	Bit.5	Bit.4	Bit.3	Bit.2	Bit.1	Bit.0
4006h	Reserved	Copy No.			Soket No.			
Soket No.: Socket Number Copy No.: Copy Number The card may use to distinguish between similar cards installed in a system.								

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9.4 Card Status Register (Address:4100h)

Address	Bit.7	Bit.6	Bit.5	Bit.4	Bit.3	Bit.2	Bit.1	Bit.0
4100h	ADM	ADS	SRESET	CMWP	PWDN	CISWP	WP	RDY/BSY
ADM: ORed value of the Ready/Busy Mask Register. 1 = Any device is masked. 0 = All Devices are not Masked. ADS: ORed value of the Sleep Control Register. 1 = Any device-pair is Controled power-down by bit.2 of the Card Configuration Register. SRESET: Reflects the bit.7 of the Configuration Option Register. CMWP: Reflects the bit.1 of the Write Protection Register. PWDN: Reflects the bit.2 of the Card Configuration Register. CISWP: Reflects the bit.0 of the Write Protection Register. WP: Indicates the Write Protect Switch status. 1 = Write Protect Switch: ON 1 = Write Protect Switch: OFF RDY/BSY: Reflects the Ready/Busy Status Register. 1 = All devices are READY. 0 = Any device is BUSY.								

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9. 5 Write Protection Register (Address:4104h)

Address	Bit.7	Bit.6	Bit.5	Bit.4	Bit.3	Bit.2	Bit.1	Bit.0
4104h	Reserved					BLKEN	CMWP	CISWP
BLKEN: Block Locking Enable 1 = Enable Block Locking 0 = All Blocks Unlocked CMWP: Common Memory Write Protect 1 = Common Memory without CIS region in Write Protect Status CISWP: Common Memory CIS Write Protect 1 = Common Memory CIS in Write Protect Status								

NOTE: ID242 series ignores BLKEN bit. Block Locking is always enable.

9. 6 Sleep Control Register (Address:4118h~411Ah)

Address	Bit.7	Bit.6	Bit.5	Bit.4	Bit.3	Bit.2	Bit.1	Bit.0
411Ah	Reserved							
4118h	Reserved		DEV10/11	DEV8/9	DEV6/7	DEV4/5	DEV2/3	DEV0/1
1= Select sleep mode device-pair If set to "1", the corresponding device-pairs are putted into deep power-down mode by PWDN bit of Configuration Status Register.								

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9. 7 Ready/Busy Mask Register (Address:4120h~4122h)

Address	Bit.7	Bit.6	Bit.5	Bit.4	Bit.3	Bit.2	Bit.1	Bit.0
4122h	Reserved				DEV11	DEV10	DEV9	DEV8
4120h	DEV7	DEV6	DEV5	DEV4	DEV3	DEV2	DEV1	DEV0
1 = Mask the Rdy/Bsy# The corresponding device's Rdy/Bsy# signals to set bit are ignored for card's RDY/BSY# output.								

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9. 8 Ready/Busy Status Register (Address:4130h~4132h)

Address	Bit.7	Bit.6	Bit.5	Bit.4	Bit.3	Bit.2	Bit.1	Bit.0
4132h	Reserved				DEV11	DEV10	DEV9	DEV8
4130h	DEV7	DEV6	DEV5	DEV4	DEV3	DEV2	DEV1	DEV0
1=READY 0=BUSY Each bit indicates the corresponding device's Rdy/Bsy# signal.								

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9. 9 Ready/Busy Mode Register (Address:4140h)

Address	Bit.7	Bit.6	Bit.5	Bit.4	Bit.3	Bit.2	Bit.1	Bit.0
4140h	Reserved						RACK	MODE
RACK: Ready Acknowledge Bit Must clear this bit after receiving ready status to prepare for next device's ready transition. MODE: RDY/BSY# Mode 1 = High-Performance Mode 0 = PCMCIA Mode								

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10. Command Definitions

Device operations are determined by writing specific commands to the Command User Interface. Table 9 defines the commands.

Table 9. Command Definitions

Command	Note	First Bus Cycle			Second Bus Cycle		
		Operation	Address	Data	Operation	Address	Data
Read Array / Reset		Write	DA	FFh (FFFFh)	-	-	-
Read Identifier Codes	1	Write	DA	90h (9090h)	Read	IA	ID
Read Status Register	2	Write	DA	70h (7070h)	Read	DA	SRD
Clear Status Register		Write	DA	50h (5050h)	-	-	-
Word/Byte Write	3	Write	WA	40h (4040h) or 10h (1010h)	Read	WA	WD
Block Erase	3	Write	BA	20h (2020h)	Write	BA	D0h (D0D0h)
Block Erase and Word/Byte Write Suspend	3	Write	DA	B0h (B0B0h)	-	-	-
Block Erase and Word/Byte Write Resume	3	Write	DA	D0h (D0D0h)	-	-	-
Set Block Lock-Bit		Write	BA	60h (6060h)	Write	BA	01h (0101h)
Set Master Lock-Bit	4	Write	DA	60h (6060h)	Write	DA	F1h (F1F1h)
Clear Block Lock-Bit		Write	DA	60h (6060h)	Write	DA	D0h (D0D0h)

Address

IA =Identifier code Address

WA =Write Address

BA =Block Address

DA =Device Address

Data

ID =Identifier Codes

WD =Write Data

SRD =Data from Status Register

Note:

- Following the Read Identifier Codes command, read operations access manufacture, device, block lock, and master lock codes.
- Status Register may be read to determine when a write, block erase, or lock bit configuration is complete, and whether that operation completed successfully.
- If the block is locked, block erase or write operations are disabled.
- This command is not available.

11. Electrical Specifications

11.1 Absolute Maximum Ratings

PARAMETER	NOTE	SYMBOL	RATING	UNIT
Supply Voltage	2	V_{CC}	-0.3 to 6.0	V
Program Voltage	2	V_{PP}	-2.0 to 14.0	V
Input Voltage	2	V_{IN}	-0.3 to $V_{CC}+0.3$ (Max:6.0)	V
Operating Temperature	1	T_{OPR}	0 to 60	°C
Storage Temperature		T_{STG}	-20 to 65	°C

NOTES:

- Operating temperature is for commercial product defined by this specification.
- All specified voltages are with respect to GND. During transitions, this level may undershoot to -2.0v for periods <20ns or overshoot to $V_{CC}+2.0v$ for periods <20ns.

11.2 Recommended Operating Conditions

PARAMETER	NOTE	SYMBOL	MIN	MAX	UNIT
Supply Voltage		V_{CC1}	3.0	3.6	V
		V_{CC2}	4.75	5.25	V
		V_{CC3}	4.5	5.5	V
Program Voltage		V_{PP1}	3.0	3.6	V
		V_{PP2}	4.5	5.5	V
		V_{PP3}	11.4	12.6	V
Operating Temperature		T_{OPR}	0	60	°C

11.3 Capacitance

$T_a=25^{\circ}\text{C}$, $f=1\text{MHz}$

PARAMETER	SYMBOL	MIN	TYP	MAX	UNIT	CONDITION
Input Capacitance	C_{IN}	-	15	-	pF	$V_{IN}=0.0V$
Input/Output Capacitance	C_{IO}	-	25	-	pF	$V_{OUT}=0.0V$

11.4 AC Input/Output Test Conditions

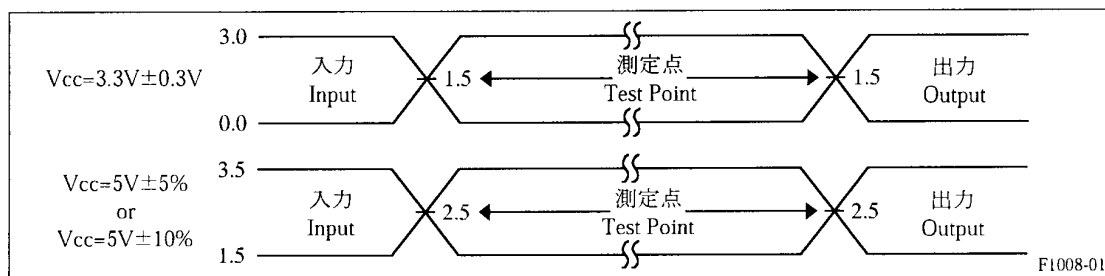


Figure 5. Transient Input/Output Reference Waveform

Figure 8 shows Input/Output level and test level for AC test. Input rise and fall times (10% to 90%) < 10ns.

12. DC Characteristics

(Ta = 0 to 60°C)

PARAMETER	SYM-BOL	NO-TE	Densi-ty	Vcc=3.3V ± 0.3V		Vcc=5V ± 5% Vcc=5V ± 10%		UNIT	TEST CONDITION
				MIN	MAX	MIN	MAX		
Input Low Voltage	V _{IL}	1			0.3Vcc		1.5	V	
Input High Voltage	V _{IH}	1		0.7Vcc		3.5		V	
Input Low Current	-I _{IL1}	2			± 2.0		± 2.0	μ A	V _I = 0V
	-I _{IL2}	3		2.0	30.0	8.0	60.0	μ A	V _I = 0V
Input High Current	I _{IH1}	3			± 2.0		± 2.0	μ A	V _I = Vcc
	I _{IH2}	2		2.0	30.0	8.0	60.0	μ A	V _I = Vcc
Output Low Voltage	V _{OL1}	4,5			-		0.4	V	I _{OL} = 6mA
					0.4		-	V	I _{OL} = 3mA
Output High Voltage	V _{OH1}	4		-		4.0		V	I _{OH} = -3mA
				Vcc-0.5		-		V	I _{OH} = -1.5mA
	V _{OH2}	5		-		4.0		V	I _{OH} = -6mA
				Vcc-0.5		-		V	I _{OH} = -3mA
Vcc Stand-by Current	I _{CCS}	6	2MB		240		240	μ A	CE ₁ #,CE ₂ #=Vcc A ₀ ~A ₂₅ =GND I _{OUT} =0mA
			4MB		450		450	μ A	
			8MB		850		850	μ A	
			10MB		1050		1050	μ A	
			16MB		850		850	μ A	
			20MB		1050		1050	μ A	
Vcc Deep Power-Down Current	I _{CCD}	6	2MB		45		75	μ A	RESET=Vcc CE ₁ #,CE ₂ #=Vcc A ₀ ~A ₂₅ =GND I _{OUT} =0mA
			4MB		70		110	μ A	
			8MB		120		170	μ A	
			10MB		145		205	μ A	
			16MB		185		205	μ A	
			20MB		225		250	μ A	
Vcc Read Current	I _{CCR}	6,8			90		100	mA	CE ₁ #,CE ₂ #=GND I _{OUT} =0mA
Vcc Word Write or Set Lock-Bit Current	I _{CCW}	6,9			35		-	mA	V _{PP} =3.3V ± 0.3V
					35		75	mA	V _{PP} =5.0V ± 10%
					25		65	mA	V _{PP} =12.0V ± 5%
Vcc Block Erase or Clear Lock-Bit Current	I _{CCE}	6,9			35		-	mA	V _{PP} =3.3V ± 0.3V
					35		65	mA	V _{PP} =5.0V ± 10%
					25		55	mA	V _{PP} =12.0V ± 5%
Vcc Word Write or Block Erase Suspend Current	I _{CCWS} I _{CCES}	6			13		21	mA	
Vcc Lockout Voltage	V _{LKO}			2.0		2.0		V	

(Continue to next page)

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DC Characteristics (Continued)

(Ta = 0 to 60°C)

PARAMETER	SYM-BOL	NO-TE	Densi-ty	Vcc=3.3V ± 0.3V		Vcc=5V ± 5% Vcc=5V ± 10%		UNIT	TEST CONDITION
				MIN	MAX	MIN	MAX		
V _{pp} Stand-by or Read Current	I _{PPS} I _{PPR}	6	2MB		+ 30		± 30	μ A	V _{PP} ≤ V _{CC}
			4MB		± 60		± 60	μ A	
			8MB		± 120		± 120	μ A	
			10MB		± 150		± 150	μ A	
			16MB		± 120		± 120	μ A	
			20MB		± 150		± 150	μ A	
			2MB		0.4		0.4	mA	V _{PP} > V _{CC}
			4MB		0.8		0.8	mA	
			8MB		1.6		1.6	mA	
			10MB		2.0		2.0	mA	
			16MB		1.6		1.6	mA	
			20MB		2.0		2.0	mA	
V _{pp} Deep Power-Down Current	I _{PPD}	6	2MB		10		10	μ A	
			4MB		20		20	μ A	
			8MB		40		40	μ A	
			10MB		50		50	μ A	
			16MB		40		40	μ A	
			20MB		50		50	μ A	
V _{pp} Word Write or Set Lock-Bit Current	I _{PPW}	6,9			80		-	mA	V _{PP} =3.3V ± 0.3V
					80		80	mA	V _{PP} =5.0V ± 10%
					32		32	mA	V _{PP} =12.0V ± 5%
V _{pp} Block Erase or Clear Lock-Bit Current	I _{PPE}	6,9			40		-	mA	V _{PP} =3.3V ± 0.3V
					40		40	mA	V _{PP} =5.0V ± 10%
					32		32	mA	V _{PP} =12.0V ± 5%
V _{pp} Word Write or Block Erase Suspend Current	I _{PPWS} I _{PPES}	6	2MB		400		400	μ A	V _{PP} ≤ V _{CC}
			4MB		430		430	μ A	
			8MB		500		500	μ A	
			10MB		530		530	μ A	
			16MB		500		500	μ A	
			20MB		530		530	μ A	
			2MB		0.4		0.4	mA	V _{PP} > V _{CC}
			4MB		0.8		0.8	mA	
			8MB		1.6		1.6	mA	
			10MB		2.0		2.0	mA	
			16MB		1.6		1.6	mA	
			20MB		2.0		2.0	mA	
V _{pp} Lockout Voltage	V _{FPLK}	7,9			1.5		1.5	V	

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NOTE:

1. These parameters are applied to all input pins and all i/put/output pins in input mode.
2. These parameters are applied to A₀~A₂₅ and D₀~D₁₅ in input mode.
3. These parameters are applied to CE₁#,CE₂#,WE#,OE#,REG# and RESET.
4. These parameters are applied to RDY/BSY#.
5. These parameters are applied to D₀~D₁₅ in output mode.
6. All currents are in RMS unless otherwise notes.
7. Block erase, word/byte write, and lock-bit configurations are inhibited when V_{pp} ≤ V_{FPLK}, and guaranteed in the V_{PP} Voltage is V_{PP1}, V_{PP2} or V_{PP3}.
8. Automatic Power Savings(APS) reduces typical I_{CCR} to 30mA at Vcc=5V and 20mA at Vcc=3.3V in static operation.
9. Sampled.

13. AC Characteristics

Testing Conditions :

- | | | |
|----------------------------------------|---|------------------------------------------------------------------------------------------------------------------------------------------------|
| 1) Input Pulse Level | : | 1.5 to 3.5V (@V _{cc} =5V±5%, V _{cc} =5V±10%)
0 to 3.0V (@V _{cc} =3.3±0.3V) |
| 2) Input Rise/Fall Time | : | 10ns |
| 3) Input/Output Timing Reference Level | : | 2.5V (@V _{cc} =5V±5%, V _{cc} =5V±10%)
1.5V (@V _{cc} =3.3V±0.3V) |
| 4) Output Load | : | 1TTL+100pF (@V _{cc} =5V±5%, V _{cc} =5V±10%)
(including scope and jig capacitance) 1TTL+50pF (@V _{cc} =3.3V±0.3V) |

13.1 Common Memory Read Operations

(Ta = 0 to 60°C)

PARAMETER	SYMBOL		V _{cc} =3.3V±0.3V		V _{cc} =5V±5%		V _{cc} =5V±10%		Unit
	IEEE	JEIDA/ PCMCIA	MIN	MAX	MIN	MAX	MIN	MAX	
Read Cycle Time	t _{AVAV}	t _{cR}	250	-	150	-	160	-	ns
Address Access Time	t _{AVQV}	t _a (A)	-	250	-	150	-	160	
CE# Access Time	t _{ELQV}	t _a (CE)	-	250	-	150	-	160	
OE# Access Time	t _{GLQV}	t _a (OE)	-	125	-	75	-	80	
Output Disable Time from CE1#,CE2# *	t _{EHQZ}	t _{dis} (CE)	-	100	-	75	-	80	
Output Disable Time from OE# *	t _{GHQZ}	t _{dis} (OE)	-	100	-	75	-	80	
Output Enable Time from CE1#,CE2#	t _{ELQNZ}	t _{en} (CE)	5	-	5	-	5	-	
Output Enable Time from OE#	t _{GLQNZ}	t _{en} (OE)	5	-	5	-	5	-	
Data Valid Time from Address Change		t _v (A)	0	-	0	-	0	-	

*:Time until output becomes floating. (The output voltage is not defined.)

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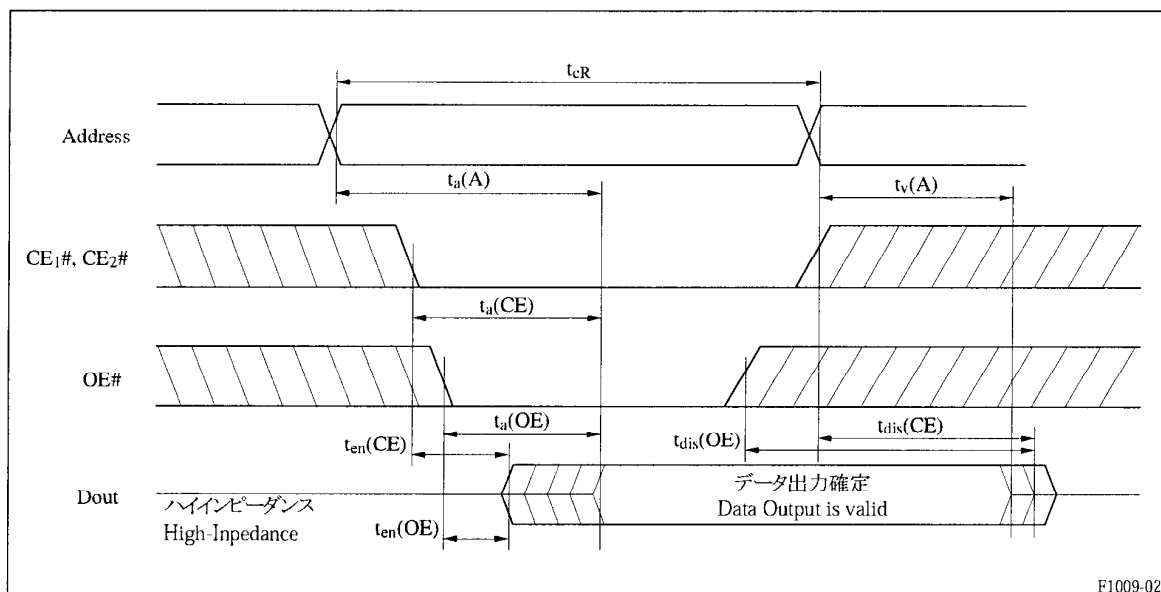


Figure 6. AC Waveforms for Read Operations

- Note) 1. WE# = "HIGH", during a read cycle.
2. Either "HIGH" or "LOW" in diagonal areas.
3. The output data becomes valid when last interval, $t_a(A)$, $t_a(CE)$ or $t_a(OE)$ have concluded.

13.2 Command Write Operations : Common Memory

13.2.1 WE# Controlled Write Operations

(V_{CC}=3.3V±0.3V, T_a=0 to 60°C)

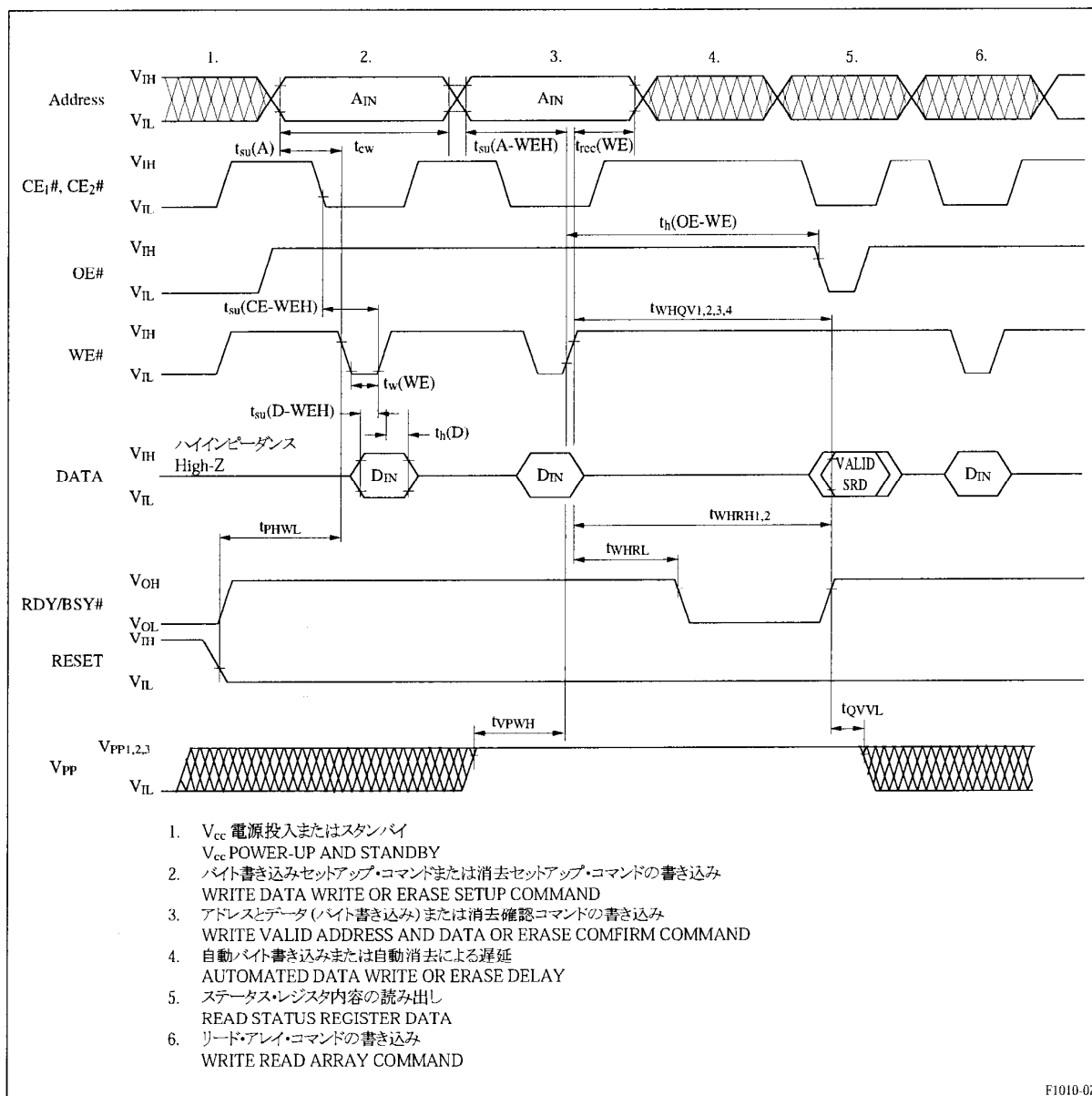
PARAMETER	SYMBOL		CONDITION	V _{CC} =3.3V±0.3V		Unit
	IEEE	PCMCIA		MIN	MAX	
Write Cycle Time	t _{AVAV}	t _{cW}		250	-	ns
Address Setup Time	t _{AVWL}	t _{su} (A)		30	-	ns
Write Recovery Time	t _{WHAX}	t _{rec} (WE)		30	-	ns
Data Setup Time for WE#	t _{DVWH}	t _{su} (D-WEH)		80	-	ns
Data Hold Time	t _{WHDx}	t _h (D)		30	-	ns
OE# Hold Time from WE#	t _{WHGL}	t _h (OE-WE)		120	-	ns
CE# Setup Time for WE#	t _{ELWH}	t _{su} (CE-WEH)		180	-	ns
Address Setup Time for WE#	t _{AVWH}	t _{su} (A-WEH)		180	-	ns
Write Pulse Width	t _{WLWH}	t _w (WE)		150	-	ns
WE# High to RDY/BSY# going Low	t _{WHRL}			-	140	ns
RESET Recovery Time	t _{PHWL}			1	-	μs
V _{PP} Setup Time	t _{VPWH}			180	-	ns
V _{PP} Hold Time	t _{QVVL}			0	-	ns
Word/Byte Write Time	t _{WHQV1}		V _{PP} =3.3V±0.3V	15	-	μs
			V _{PP} =5V±10%	8.2	-	μs
			V _{PP} =12V±5%	6.7	-	μs
Block Erase Time	t _{WHQV2}		V _{PP} =3.3V±0.3V	1.5	-	s
			V _{PP} =5V±10%	1.0	-	s
			V _{PP} =12V±5%	0.8	-	s
Set Lock-Bit Time	t _{WHQV3}		V _{PP} =3.3V±0.3V	18	-	μs
			V _{PP} =5V±10%	11.2	-	μs
			V _{PP} =12V±5%	9.7	-	μs
Clear Block Lock-Bits Time	t _{WHQV4}		V _{PP} =3.3V±0.3V	1.5	-	s
			V _{PP} =5V±10%	1.0	-	s
			V _{PP} =12V±5%	0.8	-	s
Word / byte Suspend Latency Time to Read	t _{WHRH1}		V _{PP} =3.3V±0.3V	-	10.0	μs
			V _{PP} =5V±10%	-	9.3	μs
			V _{PP} =12V±5%	-	10.4	μs
Erase Suspend Latency Time to Read	t _{WHRH2}		V _{PP} =3.3V±0.3V	-	21.1	μs
			V _{PP} =5V±10%	-	17.2	μs
			V _{PP} =12V±5%	-	17.2	μs

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(V_{CC}=5V±5%, V_{CC}=5V±10%, T_a = 0 to 60°C)

PARAMETER	SYMBOL		CONDITION	V _{CC} =5V±5%		V _{CC} =5V±10%		Unit
	IEEE	PCMCIA		MIN	MAX	MIN	MAX	
Write Cycle Time	t _{AVAV}	t _{cw}		150	-	150	-	ns
Address Setup Time	t _{AVWL}	t _{su} (A)		20	-	20	-	ns
Write Recovery Time	t _{WHAX}	t _{rec} (WE)		20	-	20	-	ns
Data Setup Time for WE#	t _{DVWH}	t _{su} (D-WEH)		50	-	50	-	ns
Data Hold Time	t _{WHDX}	t _h (D)		20	-	20	-	ns
OE# Hold Time from WE#	t _{WHGL}	t _h (OE-WE)		80	-	80	-	ns
CE# Setup Time for WE#	t _{ELWH}	t _{su} (CE-WEH)		100	-	100	-	ns
Address Setup Time for WE#	t _{AVWH}	t _{su} (A-WEH)		100	-	100	-	ns
Write Pulse Width	t _{WLWH}	t _w (WE)		80	-	80	-	ns
WE# High to RDY/BSY# going Low	t _{WHRL}			-	140	-	140	ns
RESET Recovery Time	t _{PHWL}			1	-	1	-	μs
V _{PP} Setup Time	t _{VPWH}			100	-	100	-	ns
V _{PP} Hold Time	t _{QVVL}			0	-	0	-	ns
Word/Byte Write Time	t _{WHQV1}		V _{PP} =5V±10%	6.5	-	6.5	-	μs
			V _{PP} =12V±5%	4.8	-	4.8	-	μs
Block Erase Time	t _{WHQV2}		V _{PP} =5V±10%	0.9	-	0.9	-	s
			V _{PP} =12V±5%	0.3	-	0.3	-	s
Set Lock-Bit Time	t _{WHQV3}		V _{PP} =5V±10%	9.5	-	9.5	-	μs
			V _{PP} =12V±5%	7.8	-	7.8	-	μs
Clear Block Lock-Bits Time	t _{WHQV4}		V _{PP} =5V±10%	0.9	-	0.9	-	s
			V _{PP} =12V±5%	0.3	-	0.3	-	s
Word / byte Suspend Latency Time to Read	t _{WHRH1}		V _{PP} =5V±10%	-	7.0	-	7.0	μs
			V _{PP} =12V±5%	-	7.5	-	7.5	μs
Erase Suspend Latency Time to Read	t _{WHRH2}		V _{PP} =5V±10%	-	13.1	-	13.1	μs
			V _{PP} =12V±5%	-	12.6	-	12.6	μs

T1049-01



F1010-02

Figure 7. AC Waveforms for Write Operations (WE# Controlled)

Note) While the data signal is in output mode, do not apply an opposite phase input signal.

13. 2. 2 CE# Controlled Write Operations

(V_{CC}=3.3V ± 0.3V Ta = 0 to 60°C)

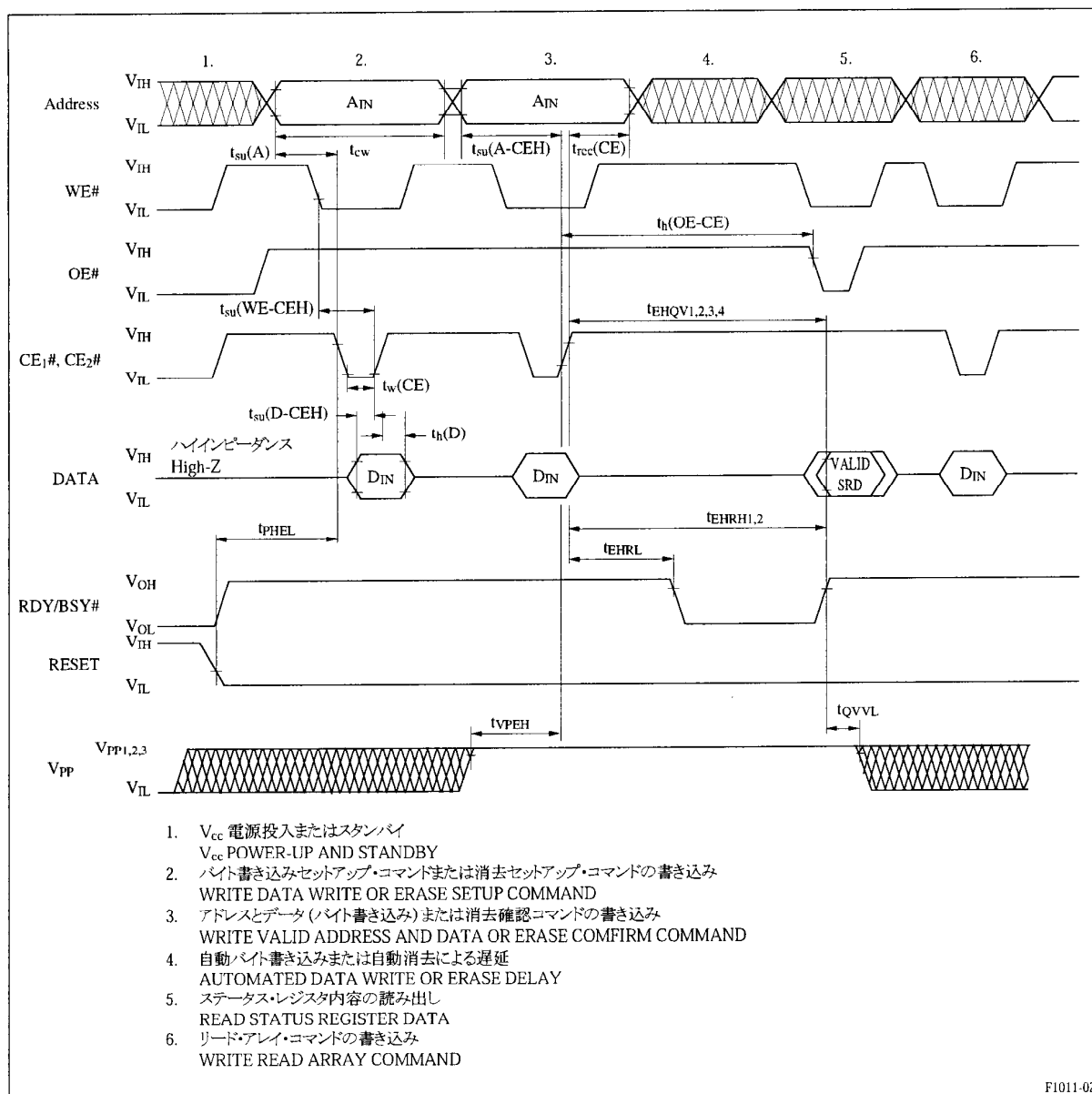
PARAMETER	SYMBOL		CONDITION	V _{CC} =3.3V ± 0.3V		Unit
	IEEE	PCMCIA		MIN	MAX	
Write Cycle Time	t _{AVAV}	t _{cw}		250	-	ns
Address Setup Time	t _{AVEL}	t _{su} (A)		30	-	ns
Write Recovery Time	t _{EHAX}	t _{rec} (CE)		30	-	ns
Data Setup Time for CE#	t _{DVEH}	t _{su} (D-CEH)		60	-	ns
Data Hold Time	t _{EHDX}	t _h (D)		30	-	ns
OE# Hold Time from CE#	t _{EHGL}	t _h (OE-CE)		120	-	ns
WE# Setup Time for CE#	t _{WLEH}	t _{su} (WE-CEH)		180	-	ns
Address Setup Time for CE#	t _{AVEH}	t _{su} (A-CEH)		180	-	ns
Write Pulse Width	t _{ELEH}	t _w (CE)		150	-	ns
CE# High to RDY/BSY# going Low	t _{EHRH}			-	140	ns
RESET Recovery Time	t _{PHL}			1	-	μs
V _{PP} Setup Time	t _{VPEH}			180	-	ns
V _{PP} Hold Time	t _{QVVL}			0	-	ns
Word/Byte Write Time	t _{EHQV1}		V _{PP} =3.3V ± 0.3V	15	-	μs
			V _{PP} =5V ± 10%	8.2	-	μs
			V _{PP} =12V ± 5%	6.7	-	μs
Block Erase Time	t _{EHQV2}		V _{PP} =3.3V ± 0.3V	1.5	-	s
			V _{PP} =5V ± 10%	1.0	-	s
			V _{PP} =12V ± 5%	0.8	-	s
Set Lock-Bit Time	t _{EHQV3}		V _{PP} =3.3V ± 0.3V	18	-	μs
			V _{PP} =5V ± 10%	11.2	-	μs
			V _{PP} =12V ± 5%	9.7	-	μs
Clear Block Lock-Bits Time	t _{EHQV4}		V _{PP} =3.3V ± 0.3V	1.5	-	s
			V _{PP} =5V ± 10%	1.0	-	s
			V _{PP} =12V ± 5%	0.8	-	s
Word / byte Suspend Latency Time to Read	t _{EHRH1}		V _{PP} =3.3V ± 0.3V	-	10.0	μs
			V _{PP} =5V ± 10%	-	9.3	μs
			V _{PP} =12V ± 5%	-	10.4	μs
Erase Suspend Latency Time to Read	t _{EHRH2}		V _{PP} =3.3V ± 0.3V	-	21.1	μs
			V _{PP} =5V ± 10%	-	17.2	μs
			V _{PP} =12V ± 5%	-	17.2	μs

T1045-01

(V_{CC}=5V ± 5%, V_{CC}=5V ± 10%, T_A=0 to 60°C)

PARAMETER	SYMBOL		CONDITION	V _{CC} =5V ± 5%		V _{CC} =5V ± 10%		Unit
	IEEE	PCMCIA		MIN	MAX	MIN	MAX	
Write Cycle Time	t _{AVAV}	t _{cw}		150	-	150	-	ns
Address Setup Time	t _{AVEL}	t _{su(A)}		20	-	20	-	ns
Write Recovery Time	t _{EHAX}	t _{rec(CE)}		20	-	20	-	ns
Data Setup Time for CE#	t _{DVEH}	t _{su(D-CEH)}		50	-	50	-	ns
Data Hold Time	t _{EHDX}	t _{h(D)}		20	-	20	-	ns
OE# Hold Time from CE#	t _{EHGL}	t _{h(OE-CE)}		80	-	80	-	ns
WE# Setup Time for CE#	t _{WLEH}	t _{su(WE-CEH)}		100	-	100	-	ns
Address Setup Time for CE#	t _{AVEH}	t _{su(A-CEH)}		100	-	100	-	ns
Write Pulse Width	t _{ELEH}	t _{w(CE)}		80	-	80	-	ns
CE# High to RDY/BSY# going Low	t _{EHRL}			-	140	-	140	ns
RESET Recovery Time	t _{PHEL}			1	-	1	-	μs
V _{PP} Setup Time	t _{VPEH}			100	-	100	-	ns
V _{PP} Hold Time	t _{QVVL}			0	-	0	-	ns
Word/Byte Write Time	t _{EHQV1}		V _{PP} =5V ± 10%	6.5	-	6.5	-	μs
			V _{PP} =12V ± 5%	4.8	-	4.8	-	μs
Block Erase Time	t _{EHQV2}		V _{PP} =5V ± 10%	0.9	-	0.9	-	s
			V _{PP} =12V ± 5%	0.3	-	0.3	-	s
Set Lock-Bit Time	t _{EHQV3}		V _{PP} =5V ± 10%	9.5	-	9.5	-	μs
			V _{PP} =12V ± 5%	7.8	-	7.8	-	μs
Clear Block Lock-Bits Time	t _{EHQV4}		V _{PP} =5V ± 10%	0.9	-	0.9	-	s
			V _{PP} =12V ± 5%	0.3	-	0.3	-	s
Word / Byte Suspend Latency Time to Read	t _{EHRH1}		V _{PP} =5V ± 10%	-	7.0	-	7.0	μs
			V _{PP} =12V ± 5%	-	7.5	-	7.5	μs
Erase Suspend Latency Time to Read	t _{EHRH2}		V _{PP} =5V ± 10%	-	13.1	-	13.1	μs
			V _{PP} =12V ± 5%	-	12.6	-	12.6	μs

T1046-01



F1011-02

Figure 8. AC Waveforms for Write Operations (CE# Controlled)

Note) While the data signal is in output mode, do not apply an opposite phase input signal.

13.3 Attribute Memory Read Operation

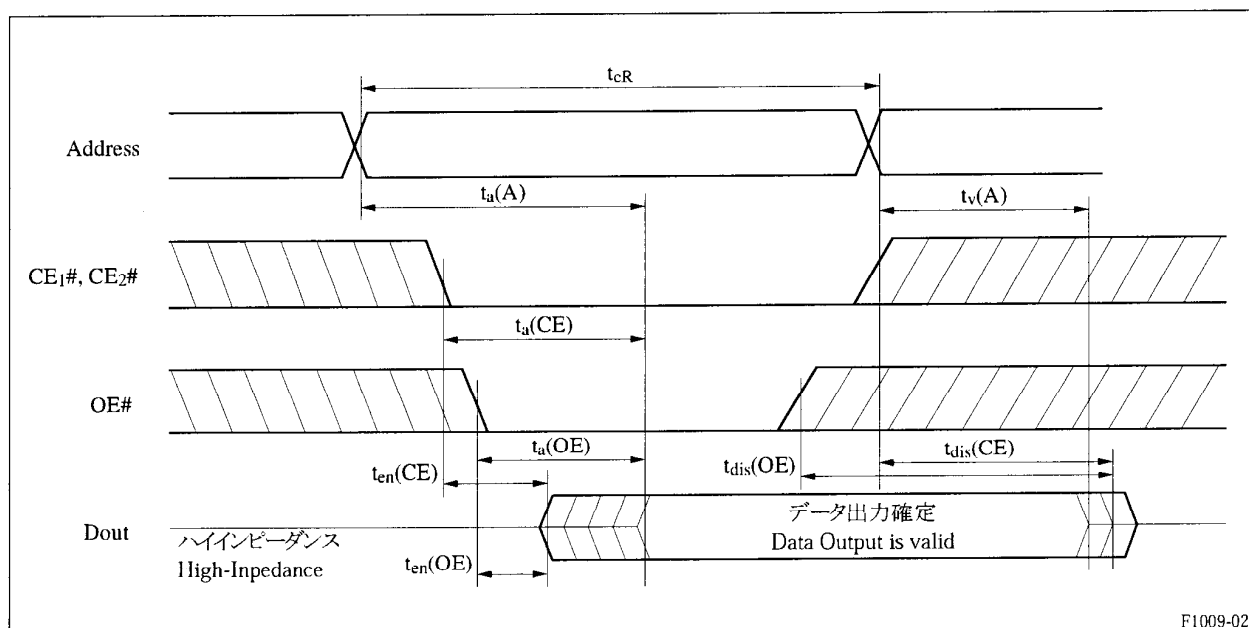
(Ta=0~60°C)

PARAMETER	SYMBOL		Vcc=3.3V±0.3V		Vcc=5V±10%		Unit
	IEEE	JEIDA/ PCMCIA	MIN	MAX	MIN	MAX	
Read Cycle Time	t_{AVAV}	t_{cR}	600	—	300	—	ns
Address Access Time	t_{AVQV}	$t_a(A)$	—	600	—	300	
CE# Access Time	t_{ELQV}	$t_a(CE)$	—	600	—	300	
OE# Access Time	t_{GLQV}	$t_a(OE)$	—	300	—	150	
Output Disable Time from CE1#,CE2# *	t_{EHQZ}	$t_{dis}(CE)$	—	150	—	100	
Output Disable Time from CE#	t_{GHQZ}	$t_{dis}(OE)$	—	150	—	100	
Output Disable Time from CE1#,CE2#	t_{ELQNZ}	$t_{en}(CE)$	5	—	5	—	
Output Disable Time from OE#	t_{GLQNZ}	$t_{en}(OE)$	5	—	5	—	
Data Valid Time from Address Change		$t_v(A)$	0	—	0	—	

*: Time until becomes floating. (The output voltage is not defined)

T1056-01

Note) When the CIS constructed by EEPROM, this card requires 5V voltage for Vcc.



F1009-02

Figure 9. Attribute Memory Read Operation

13. 4 Attribute Memory Write Operation

(Ta=0~60°C)

PARAMETER	SYMBOL		V _{CC} =3.3V ± 0.3V		V _{CC} =5V ± 10%		Unit
	IEEE	JEIDA/ PCMCIA	MIN	MAX	MIN	MAX	
Write Cycle Time	t _{AVAV}	t _{cw}	600	—	250	—	ns
Address Setup Time	t _{AVWL}	t _{su} (A)	50	—	30	—	ns
Write Recovery Time	t _{WHAX}	t _{rec} (WE)	70	—	30	—	ns
Data Setup Time	t _{DVWH}	t _{su} (D-WEH)	150	—	80	—	ns
Data Hold Time	t _{WHDX}	t _h (D)	70	—	30	—	ns
Address Setup Time for WE#	t _{AVWH}	t _{su} (A-WEH)	350	—	180	—	ns
Write Pulse Width	t _{WLWH}	t _w (WE)	300	—	150	—	ns
Setup Time for OE#	t _{GHWL}	t _{su} (OE-WE)	35	—	10	—	ns
Hold Time for OE#	t _{WHGL}	t _h (OE-WE)	35	—	10	—	ns
Setup Time for CE#	t _{ELWH}	t _{su} (CE)	0	—	0	—	ns
Hold Time for CE#	t _{GHEH}	t _h (CE)	35	—	20	—	ns

T1057-01

Note) When the CIS constructed by EEPROM, this card requires 5V voltage for V_{CC}.

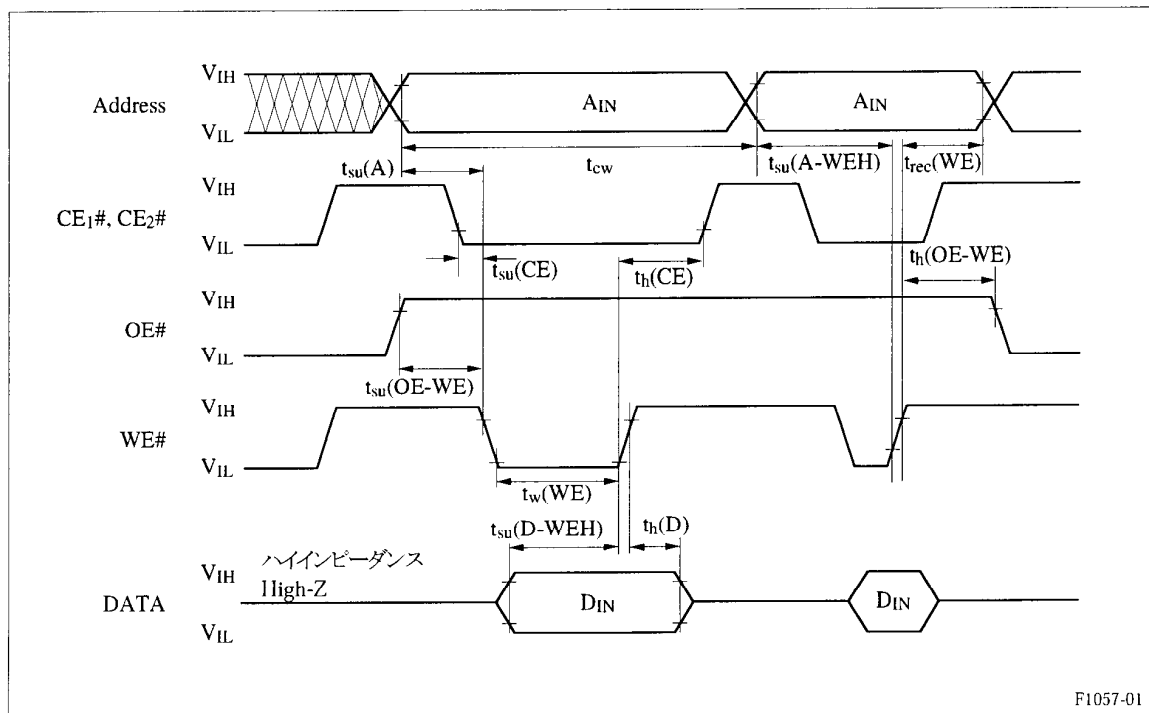


Figure 10. Attribute Memory Write Operation

13.5 Power-Up/Power Down

PARAMETER	SYMBOL	NOTES	MIN	MAX	UNITS
	PCMCIA				
CE# Signal Level ($0.0V < V_{CC} < 2.0V$)	V_i (CE)	1	0	V_{iMAX}	V
CE# Signal Level ($2.0V < V_{CC} < V_{IH}$)		1	$V_{CC}-0.1$	V_{iMAX}	V
CE# Signal Level ($V_{IH} < V_{CC}$)		1	V_{IH}	V_{iMAX}	V
CE# Setup Time	$t_{su}(V_{CC})$	—	20	—	ms
RESET Setup Time	$t_{su}(\text{RESET})$	—	20	—	ms
CE# Recover Time	$t_{rec}(V_{CC})$	—	1.0	—	μs
V_{CC} Rising Time	t_{pr}	2	0.1	300	ms
V_{CC} Falling Time	t_{pf}	2	3.0	300	ms
RESET Width	$t_w(\text{RESET})$	—	10	—	μs
RESET Width	$t_h(\text{Hi-Z RESET})$	—	1	—	ms
RESET Width	$t_s(\text{Hi-Z RESET})$	—	0	—	ms

NOTES:

1. V_{iMAX} means Absolute Maximum Voltage for input in the period of $0.0V < V_{CC} < 2.0V$, V_i (CE#) is only $0.00V-V_{iMAX}$
2. The t_{pr} and t_{pf} are defined as "linear waveforms" in the period of 10% to 90%, or vice-versa. Even if the waveform is not a "linear waveform," its rising and falling time must meet this specification.

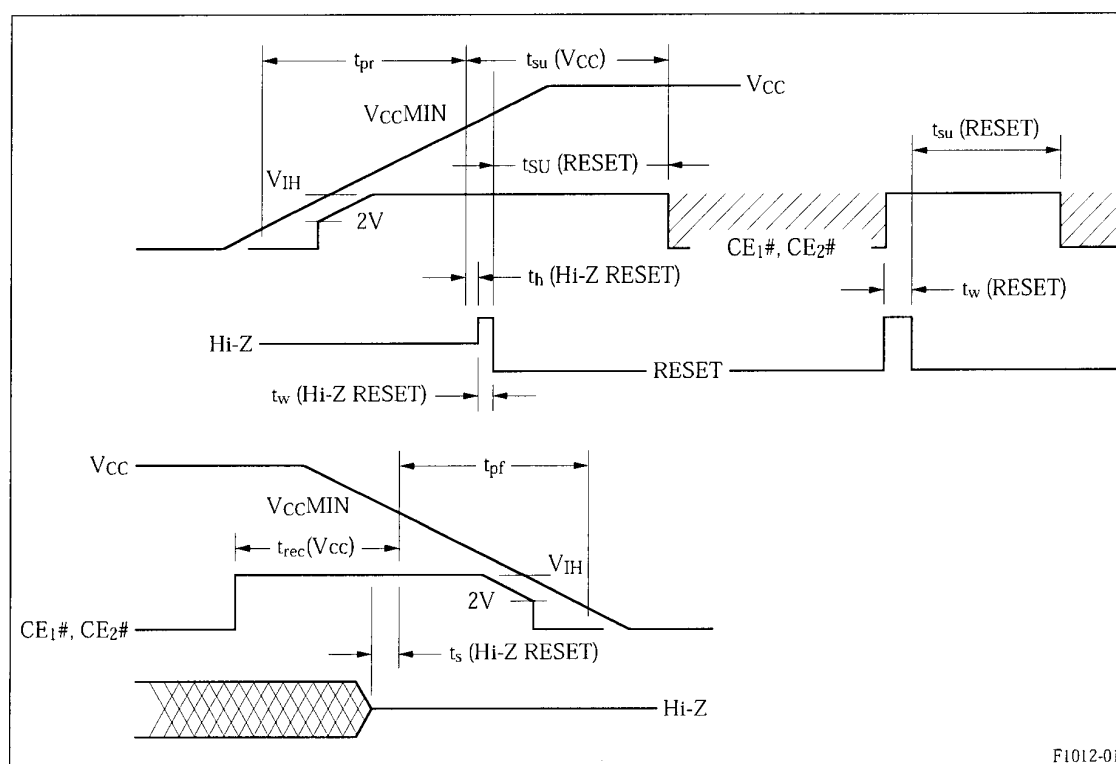


Figure 11. Power-Up/Down Timing

14. Specification Changes

This datasheet is for ID242 series product overview, and final specifications will be submitted for qualification of the memory card. Please note that contents of this datasheet may be revised without announcement beforehand. Please do NOT finalize a system design with this information.

15. Other Precautions

- Permanent damage occurs if the memory card is stressed beyond Absolute Maximum Ratings. Operation beyond the Recommended Operating Conditions is not recommended and extended exposure beyond the Recommended Operating Conditions may affect device reliability.
- Writing to the memory card can be prevented by switching on the write protect switch on the end of the memory card.
- Avoid allowing the memory card connectors to come in contact with metals and avoid touching the connectors, as the internal circuits can be damaged by static electricity.
- Avoid storing in direct sunlight, high temperatures (do not place near heaters or radiators), high humidity and dusty areas.
- Avoid subjecting the memory card to strong physical abuse. Dropping, bending, smashing or throwing the card can result in loss of function.
- When the memory card is not being used, return it to its protective case.
- Do not allow the memory card to come in contact with fire.

16. External Diagrams

